Current Limit Switch, with OVP and TRCB, 28 V / 5 A Rated

FPF2895C

WLCSP24 2.6x1.67x0.612
CASE 567TQ

Description

The FPF2895C features a 28 V and 5 A rated current limit power switch, which offers Over−Current Protection (OCP), Over−Voltage Protection (OVP), and True Reverse Current Block (TRCB) to protect system. It has low On−resistance of typical 27 mΩ with WL−CSP can operate over an input voltage range of 4 V to 22 V.

The FPF2895C supports ±10% of current limit accuracy, flexible operations such as selectable OVP, selectable ON polarity and selectable OCP behavior, which can be optimized according to system requirements.

The FPF2895C is available in a 24−bump, 1.67 mm x 2.60 mm Wafer−Level Chip−Scale Package (WLCSP) with 0.4 mm pitch.

Features

- 28 V / 5 A Capability
- Wide Input Voltage Range: 4 V ~ 22 V
- Ultra Low On−Resistance
  - Typ. 27 mΩ at 5 V and 25 °C
- Adjustable Current Limit with external RSET
  - 500 mA ~ 5 A
- Selectable OVLO with OV1 and OV2 Logic Input
  - 5.95 V ± 50 mV
  - 10 V ± 100 mV
  - 16.8 V ± 300 mV
  - 23 V ± 460 mV
- Selectable ON Polarity
- Selectable Over-Current Behavior
  - Auto−Restart Mode
  - Current Source Mode
- True Reverse Current Block
- Thermal Shutdown
- Open Drain Fault FLAGB Output
- UL60950−1, IEC60950−1 and IEC62368−1 Certification 5 A Max Loading
- Robust ESD Capability
  - 2 kV HBM & 1 kV CDM
 - 15 kV Air Discharge & 8 kV Contact Discharge under IEC 61000−4−2
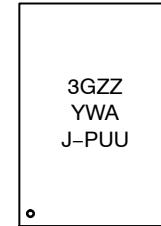
Applications

- Laptop, Desktop Computing and Monitor
- Power Accessories
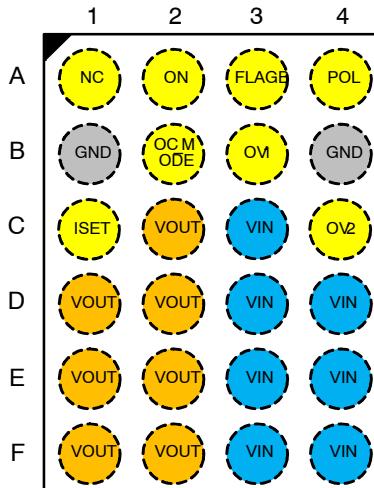
MARKING DIAGRAM

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3GZZ
YWA
J−PUU
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3G = Specific Device Code
ZZ = Assembly Lot
YW = 2−Digits Date Code
A = Assembly Location
J− = X− Coordinates with dash as separator*
P = Y Coordinates*
UU = Two Digit Wafer ID*

*For **onsemi** internal use only.

PIN CONFIGURATION

	1	2	3	4
A	NC	ON	FLAGB	POL
B	GND	OC MODE	OV1	GND
C	ISET	VOUT	VIN	OV2
D	VOUT	VOUT	VIN	VIN
E	VOUT	VOUT	VIN	VIN
F	VOUT	VOUT	VIN	VIN

ORDERING INFORMATION

FPF2895C

Application Diagram
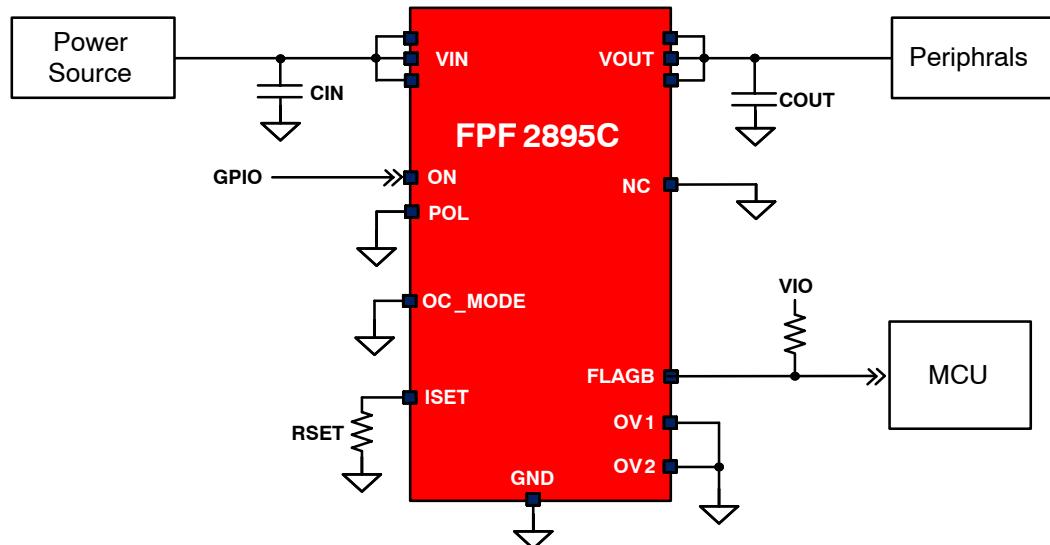
Figure 1. Typical Application

Block Diagram
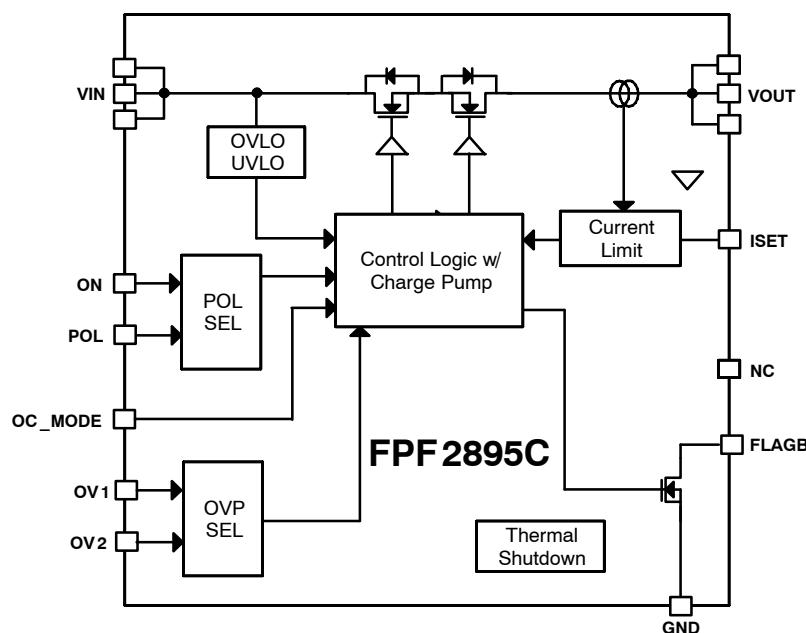
**Figure 2. Functional Block Diagram**

PIN CONFIGURATION

Pin Configuration (Top View)

Pin Configuration (Bottom View)
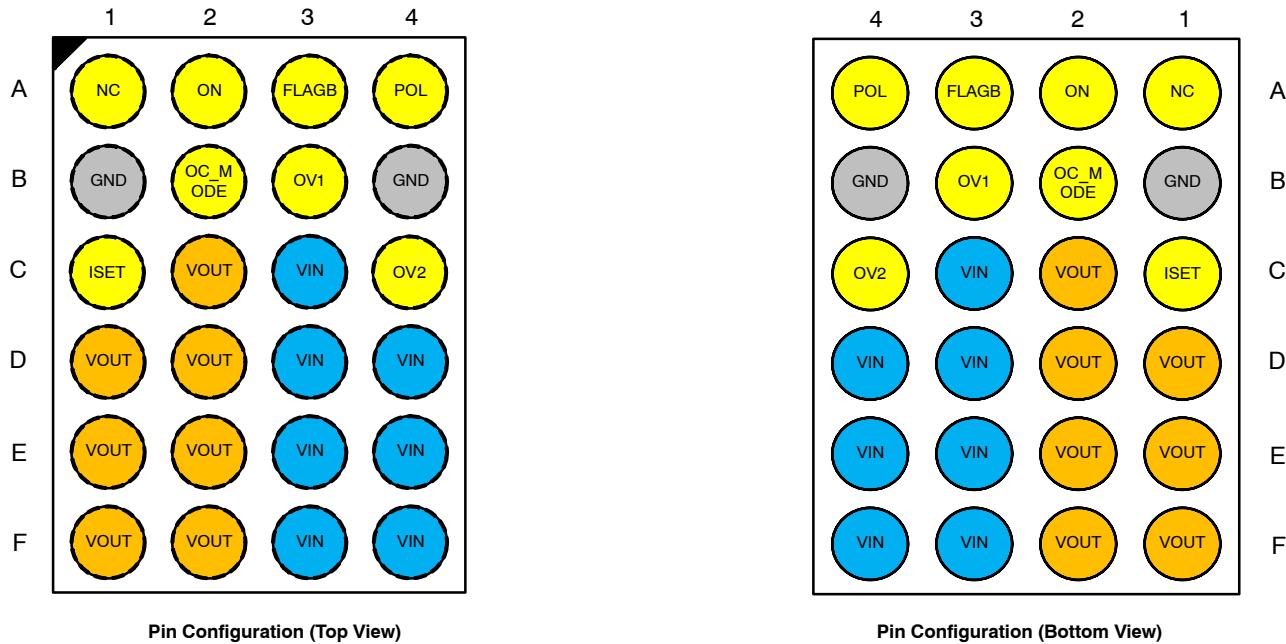
Figure 3. 24 Ball WL_CSP, 4 x 6 Array, 0.4 mm Pitch, 250 μm Ball

Table 1. PIN DEFINITIONS

Name	Bump	Type	Description
VIN	C3, D3, D4, E3, E4, F3, F4	Input/Supply	Switch Input and Device Supply
VOUT	C2, D1, D2, E1, E2, F1, F2	Output	Switch Output to Load
NC	A1	Dummy	Recommended to connect to GND
ON	A2	Input	Internal pull–down resistor of 1 MΩ is included. Active polarity is depending on POL state (Note 1)
POL	A4	Input	Enable Polarity Selection. Internal pull/up of 1 MΩ is included. HIGH (or Floating): Active LOW LOW: Active HIGH (Note 1)
FLAGB	A3	Output	Active LOW, open drain output indicates an over–current, under–voltage, over–voltage, or over–temperature state.
ISET	C1	Input	A resistor from ISET to ground set the current limit for the switch. See below selection Table 6.
OC_MODE	B2	Input	OCP behavior can be selected. Internal pull–up of 1 MΩ is included. HIGH (or Floating): Auto–restart mode during over–current condition. LOW: Current source mode during over–current condition. (Note 1)
OV1	B3	Input	Over–Voltage Selection Input 1. Internal pull–up of 1 MΩ is included and see below selection Table 7. (Note 1)
OV2	C4	Input	Over–Voltage Selection Input 2. Internal pull–up of 1 MΩ is included and see Table 7 (Note 1)
GND	B1, B4	GND	Device Ground

1. To avoid external noise influence when floating, recommend to connect these pins to a certain level.

Table 2. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min.	Max.	Unit
VIN, VOUT	VIN, VOUT to GND		−0.3	28.0	V
V_{PIN}	ON, POL, OC_MODE, ISET, FLAGB and OVn to GND		−0.3	6.0	V
I_{SW}	Continuous Switch Current		–	5.5	A
t_{PD}	Total Power Dissipation at T_A = 25°C		–	2.08	W
T_{STG}	Storage Junction Temperature		−65	+150	°C
T_J	Operating Junction Temperature		–	+150	°C
T_L	Lead Temperature (Soldering, 10 Seconds)		–	+260	°C
θ_{JA}	Thermal Resistance, Junction−to−Ambient (1in.^{2} pad of 2 oz. copper)		–	60 (Note 2)	°C/W
ESD	Electrostatic Discharge Capability	Human Body Model, ANSI/ESDA/JEDEC JS−001	2	–	kV
		Charged Device Model, JESD22−C101	1	–	
	IEC61000−4−2 System Level	Air Discharge	15	–	
		Contact Discharge	8	–	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
2. Measured using 2S2P JEDEC std. PCB.

Table 3. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Max.	Unit
V_{IN}	Supply Voltage	4.0	22.0	V
C_{IN} / C_{OUT}	Input and Output Capacitance	1.0	–	µF
T_A	Ambient Operating Temperature	−40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. ELECTRICAL CHARACTERISTICS (Unless otherwise noted, V_{IN} = 4 to 22 V, T_A = −40 to 85°C; typical values are at V_{IN} = 5 V, C_{IN} = C_{OUT} = 1 µF, ON = HIGH, POL = OV1 = OV2 = OC_MODE = GND and T_A = 25°C.)

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Unit
BASIC OPERATION							
V_{IN}	Input Voltage (Note 4)			4	–	22	V
I_{SD_IN}	V_{IN} Shutdown Current	V_{ON} = OFF, V_{IN} = 5.5 V, V_{OUT} = Short to GND		–	75	100	µA
I_Q	Quiescent Current	I_{OUT} = 0 mA, V_{ON} = ON	V_{IN} = 5 V	–	270	330	µA
			V_{IN} = 12 V	–	300	400	
			V_{IN} = 20 V	–	350	450	
R_{ON}	On Resistance	T_A = 25°C, I_{OUT} = 1 A	V_{IN} = 5 V	–	27	39	mΩ
			V_{IN} = 12 V	–	27	39	
			V_{IN} = 20 V	–	27	39	
I_{ON}	ON Input Leakage	V_{ON} = V_{IN} or GND		–	–	10	µA
V_{IH}	Logic Pin Input (ON, POL, OV1, OV2, OC_MODE) High Voltage	V_{IN} = 3 V ~ 23 V		1.2	–	–	V
V_{IL}	Logic Pin Input (ON, POL, OV1, OV2, OC_MODE) Low Voltage	V_{IN} = 3 V ~ 23 V		–	–	0.4	V
V_{P_LOW}	FLAGB Output Logic Low Voltage	V_{IN} = 5 V, I_{SINK} = 5 mA		–	0.1	0.2	V
I_{LKG}	FLAGB Output High, Leakage Current	V_{IN} = 5 V, Switch ON		–	–	1	µA

Table 4. ELECTRICAL CHARACTERISTICS (Unless otherwise noted, V_{IN} = 4 to 22 V, T_A = −40 to 85°C; typical values are at V_{IN} = 5 V, C_{IN} = C_{OUT} = 1 μF, ON = HIGH, POL = OV1 = OV2 = OC_MODE = GND and T_A = 25°C.)

PROTECTIONS

I_{LIM}	Current Limit (Note 3)	V_{IN} = 5 V, V_{OUT} = 4 V, R_{SET} = 3.01 kΩ, T_A = −40 to 85°C		1.35	1.50	1.65	A
		V_{IN} = 5 V, V_{OUT} = 4 V, R_{SET} = 1.54 kΩ, T_A = −40 to 85°C		2.85	3.00	3.15	
V_{FOLD}	ILIM Foldback Trip Voltage (Note 3)	V_{OUT} under ILIM Mode		–	2	–	V
I_{FOLD}	ILIM Foldback Current (Note 3)	V_{IN} = 5 V, V_{OUT} < V_{FOLD}, T_A = 25°C, OC_MODE = HIGH		–	500	–	mA
		V_{IN} = 5 V, V_{OUT} < V_{FOLD}, T_A = 25°C, OC_MODE = LOW		–	250	–	mA
V_{UVLO}	Under−Voltage Lockout	V_{IN} Increasing		–	2.70	2.95	V
		V_{IN} Decreasing		–	2.5	–	
	UVLO Hysteresis			–	200	–	mV
V_{OVLO}	Over−Voltage Lockout (Note 3)	OV1 = LOW, OV2 = LOW	V_{IN}Rising	22.20	23.00	23.46	V
			V_{IN}Falling	22.00	–	–	
		OV1 = LOW, OV2 = HIGH	V_{IN}Rising	9.80	10.00	10.10	
			V_{IN}Falling	9.75	–	–	
		OV1 = HIGH, OV2 = LOW	V_{IN}Rising	16.30	16.80	17.10	
			V_{IN}Falling	16.10	–	–	
		OV1 = HIGH, OV2 = HIGH	V_{IN}Rising	5.85	5.95	6.00	
			V_{IN}Falling	5.80	–	–	
T_{OVP}	OVP Response Time (Note 3)	R_L = 100 Ω, C_L = 0 μF, V_{IN} > V_{OVLO} to V_{OUT} = 0.9 × V_{IN}		–	–	150	ns
V_{T_RCB}	TRCB Protection Trip Point	$V_{OUT\ -\ IN}$		–	25	40	mV
V_{R_RCB}	TRCB Protection, Release Point	$V_{IN\ -\ OUT}$		–	25	40	mV
t_{RCB}	TRCB Response Time (Note 3)	V_{IN} = 5 V, V_{ON} = HIGH/LOW		–	5	–	μs
$t_{RCB\_Release}$	TRCB Release Time (Note 3)	V_{IN} = 5 V, Enabled		–	1	–	μs
t_{OC}	Over Current Response Time (Note 3)	V_{IN} = 5 V, Moderate OC		–	20	–	μs
		V_{IN} = 5 V, Hard Short		–	5	–	
I_{SD_OUT}	VOUT Shutdown Current	V_{ON} = OFF, V_{OUT} = 5 V, V_{IN} = Short to GND		–	–	2	μA
TSD	Thermal Shutdown (Note 3)	Shutdown Threshold		–	150	–	°C
		Hysteresis		–	20	–	

DYNAMIC BEHAVIOR

t_{DON}	Delay On Time	R_L = 100 Ω C_L = 1 μF	–	1	–	ms
t_R	V_{OUT} Rise Time	R_L = 100 Ω C_L = 1 μF	–	1	–	ms
t_{ON}	Turn−On Time	R_L = 100 Ω C_L = 1 μF	–	2	–	ms
t_{DOFF}	Delay Off Time	R_L = 100 Ω C_L = 1 μF	–	10	–	μs
t_F	V_{OUT} Fall Time	R_L = 100 Ω C_L = 1 μF	–	200	–	μs
t_{OFF}	Turn−Off Time	R_L = 100 Ω C_L = 1 μF	–	210	–	μs
t_{BLANK}	Over−Current Blanking Time (Note 3)	OC_MODE = HIGH	–	5	–	ms
t_{RSTRT}	Auto−Restart Time (Note 3)	OC_MODE = HIGH	–	200	–	ms
t_{QUAL}	Over−Current Qualification Time (Note 3)	OC_MODE = LOW	–	5	–	ms
t_{DEB}	FLAGB De−bounce Time (Note 3)	Restart−up during or after OC	–	3	–	ms
		Restart−up during or after Thermal shutdown	–	15	–	
		Restart−up during or after UVLO	–	1	–	

3. Guaranteed by characterization and design, not production test.
4. To avoid output voltage is coupled to high during cold start, the slew rate of Vin should be less than 10 mV/μs

Setting Current Limit

FPF2895C current limit is set with an external resistor connected between I_{SET} and GND. This resistor is selected using the following equation:

R_{SET} (kΩ) = 4448.6/Ilim [mA]
Resistor tolerance of 1% or less is recommended.

Table 5. ILIM VS. RSET LOOK−UP TABLE

RSET [kΩ]	ILIM [mA]		
	Min.	Typ.	Max.
8.89	450	500	550
7.41	540	600	660
6.35	630	700	770
5.56	720	800	880
4.94	810	900	990
4.45	900	1000	1100
4.04	990	1100	1210
3.71	1080	1200	1320
3.42	1170	1300	1430
3.18	1260	1400	1540
2.96	1350	1500	1650
2.78	1440	1600	1760
2.62	1530	1700	1870
2.47	1620	1800	1980
2.34	1710	1900	2090
2.22	1800	2000	2200
2.12	1890	2100	2310
2.02	1980	2200	2420
1.93	2070	2300	2530
1.85	2160	2400	2640
1.78	2250	2500	2750
1.71	2340	2600	2860
1.65	2430	2700	2970
1.59	2520	2800	3080
1.53	2610	2900	3190
1.48	2700	3000	3300
1.43	2790	3100	3410
1.39	2880	3200	3520
1.35	2970	3300	3630
1.31	3060	3400	3740
1.27	3150	3500	3850
1.24	3240	3600	3960
1.20	3330	3700	4070
1.17	3420	3800	4180
1.14	3510	3900	4290
1.11	3600	4000	4400
1.08	3690	4100	4510
1.06	3780	4200	4620
1.03	3870	4300	4730
1.01	3960	4400	4840

Table 5. ILIM VS. RSET LOOK−UP TABLE

RSET [kΩ]	ILIM [mA]		
	Min.	Typ.	Max.
0.99 (Note 5)	4050	4500	4950
0.97	4140	4600	5060
0.95	4230	4700	5170
0.93	4320	4800	5280
0.91	4410	4900	5390
0.89	4500	5000	5500

5. Passed UL&CB certification with max. 5 A output current.
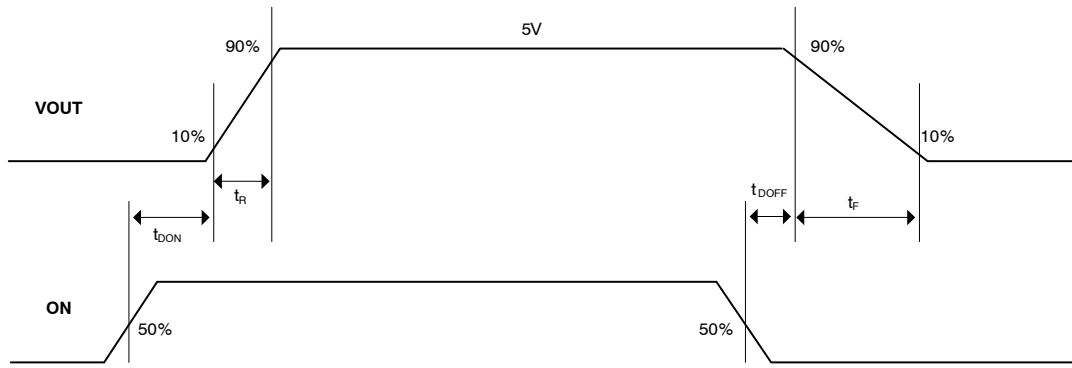
Table 6. OVLO LEVEL SELECTION

OV1	OV2	OVLO
LOW	LOW	23 V ± 460 mV
LOW	HIGH (Floating)	10 V ± 100 mV
HIGH (Floating)	LOW	16.3 ± V 300 mV
HIGH (Floating)	HIGH (Floating)	5.95 ± V 50 mV
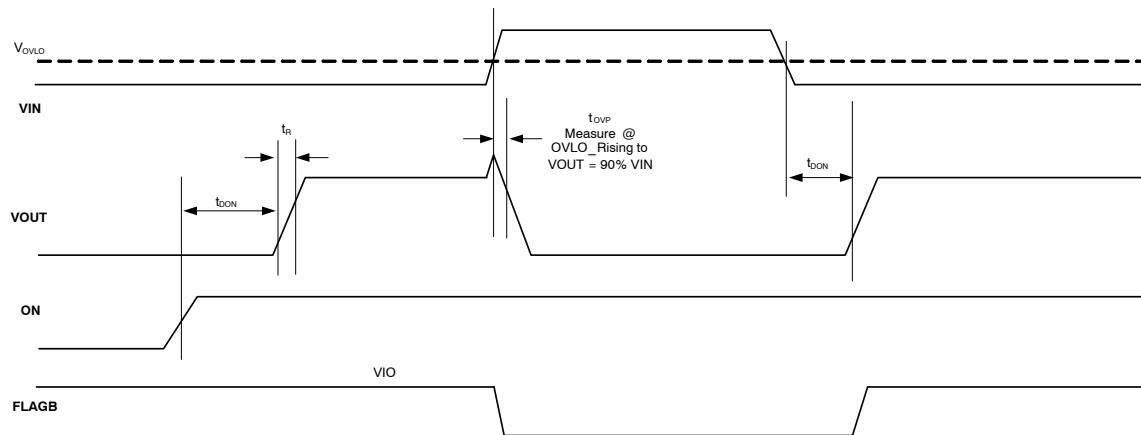
Table 7. DEVICE ENABLE POLARITY SELECTION

POL	ON	Device State	ON Polarity
LOW	LOW (Floating)	OFF	Active HIGH
LOW	HIGH	ON	
HIGH (Floating)	LOW (Floating)	ON	Active LOW
HIGH (Floating)	HIGH	OFF	
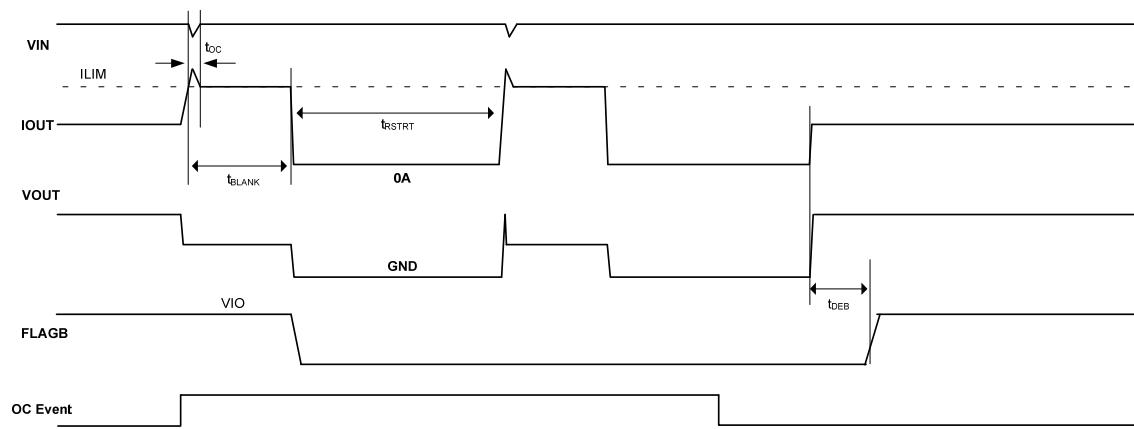
TIMING DIAGRAMS

Figure 4. Normal ON/OFF Operation by ON (POL = GND)

Figure 5. OVLO Operation (POL = GND & FLAGB is Pulled Up With an External VIO)

Figure 6. Current Limit Operation (OC_MODE=HIGH & FLAGB is Pulled Up With an External VIO)

VIN

t_{OC}

ILIM

IOUT

t_{QUAL}

VOUT

VIO

t_{DEB}

FLAGB

OC Event

Figure 7. Current Limit Operation (OC_MODE = LOW & FLAGB Is Pulled Up With an External VIO)

VIN

t_{RCB}

IOUT

0A

Peak reverse current developing V_{T_RCB} with Ron

V_{R_RCB} to release TRCB

VOUT

= VIN

> VIN

VIN $-V_F$

= VIN

$t_{RCB\_RELEASE}$

Internal FETs

ON

OFF

ON
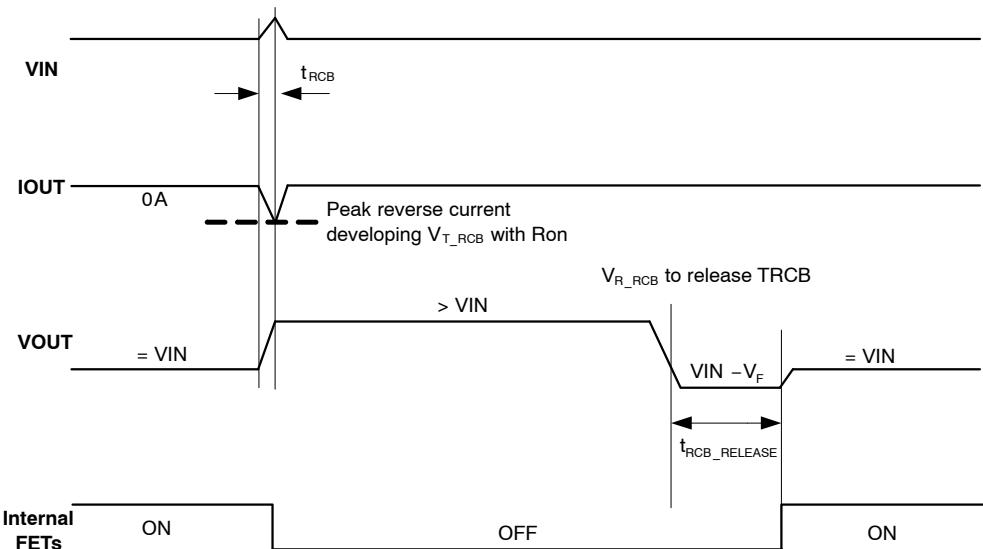
Figure 8. TRCB Operation (Device is Enabled)

VOUT

Load current above 6A within 1us, FPF2895 will turn off immediately

IOUT

I_{FOLD}

0

t_{BLANK}

t_{RSTRT}

t_{DON}

FLAGB

t_{QUAL}
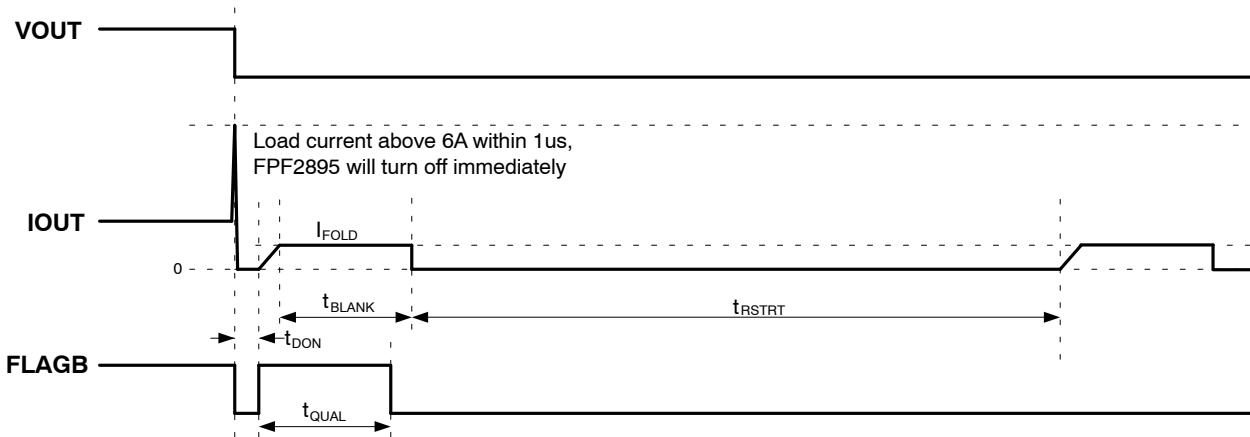
Figure 9. VOUT Hard Short to GND (OC_MODE=HIGH & FLAGB Is Pulled Up With an External VIO)

FPF2895C

PRODUCT–SPECIFIC DIMENSIONS

D	E	X	Y
2600 μm ± 30 μm	1670 μm ± 30 μm	235 μm ± 18 μm	300 μm ± 18 μm

ORDERING INFORMATION

Part Number	Operating Temperature Range	Top Mark	Package	Shipping[†]
FPF2895CUCX	−40°C – +85°C	3G	24–Ball, 0.4 mm Pitch WLCSP	Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
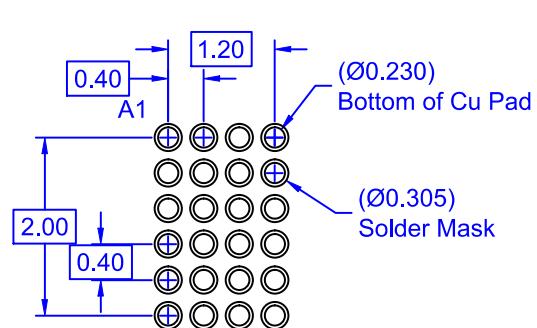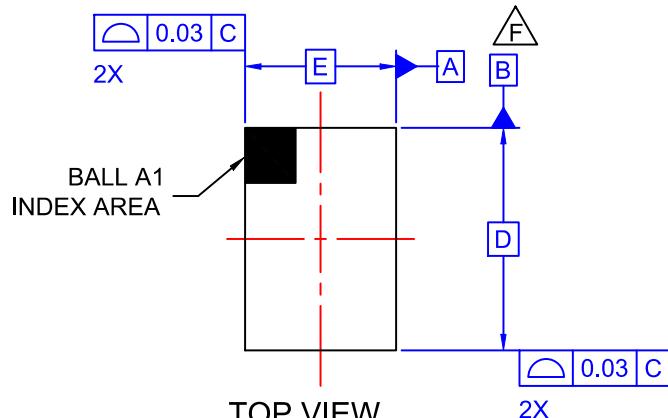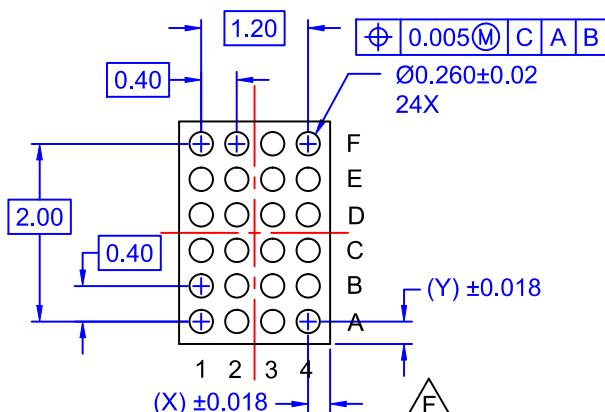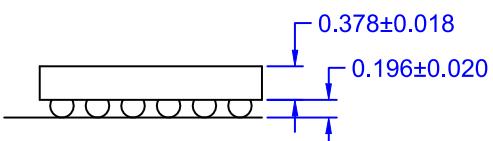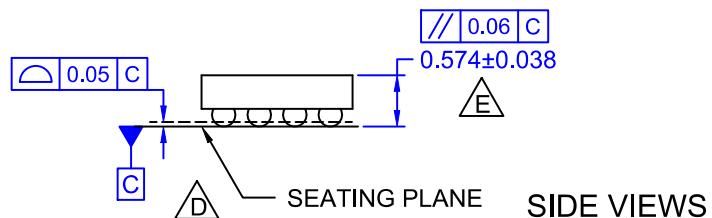
WLCSP24 2.6x1.67x0.612
CASE 567TQ
ISSUE O

DATE 31 MAR 2017

TOP VIEW

BALL A1
INDEX AREA

RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)

(Ø0.230)
Bottom of Cu Pad

(Ø0.305)
Solder Mask

1.20
0.40
A1
2.00
0.40

SIDE VIEWS

0.574±0.038

SEATING PLANE

0.378±0.018
0.196±0.020

BOTTOM VIEW

1.20
0.40
Ø0.260±0.02
24X
2.00
0.40
(Y) ±0.018
(X) ±0.018

NOTES
A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCE
   PER ASMEY14.5M, 2009.
D. DATUM C IS DEFINED BY THE SPHERICAL
   CROWNS OF THE BALLS.
E. PACKAGE NOMINAL HEIGHT IS
   574 ± 38 MICRONS (536-612 MICRONS).
F. FOR DIMENSIONS D, E, X, AND Y SEE
   PRODUCT DATASHEET.

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ADDITIONAL INFORMATION

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